L Number	Hits	Search Text	DB	Time stamp
1	52835	(polymeric polyimide polymer poymide) near4 substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/24 09:13
2	502	((polymeric polyimide polymer poymide) near4 substrate) and (trace near4 substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/24 09:14
3	149	(((polymeric polyimide polymer poymide) near4 substrate) and (trace near4 substrate)) and 257/$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/24 09:27
4	82	(((polymeric polyimide polymer poymide) near4 substrate) and (trace near4 substrate)) and (MCM (multi-chip near module) (multi near chip near module))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/24 09:46
5	21442	Yoshimura.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/24 09:46
6	1810	Yoshimura.in. and optical	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/24 09:47
7	40	(Yoshimura.in. and optical) and polymeric	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/24 09:47
-	36	(polymeric polyimide polymer polymide) same (routing route) same trace same (chip die)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 10:46
-	426	"routing element"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 10:51
-	20	("routing element" and (chip die)) and trace	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 10:52
-	117	"routing element" and (chip die)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 10:56
-	97	("routing element" and (chip die)) not (("routing element" and (chip die)) and trace)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:01
-	2879	257/723	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:01
-	1910	257/685	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:??
-	888	257/686	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/?? ?? 11:??
-	1?19	257/???	USPAT; US-PGPUB; EPO; JPO; DERWENT	??
-	1?10	257/???	USPAT; US-PGPUB; EPO; JPO; DERWENT	??

–	1949	257/784	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:02
–	2147	257/786	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:01
–	1507	257/691	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:02
–	9398	257/723 257/686 257/685 257/777 257/730 257/784 257/786 257/691	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:11
–	2629	(257/723 257/686 257/685 257/777 257/730 257/784 257/786 257/691) and (polymeric polyimide polyimide polymer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:13
–	846	((257/723 257/686 257/685 257/777 257/730 257/784 257/786 257/691) and (polymeric polyimide polyimide polymer)) and trace	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:13
–	258	(((257/723 257/686 257/685 257/777 257/730 257/784 257/786 257/691) and (polymeric polyimide polyimide polymer)) and trace) and (route routing)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:19
–	115	((((257/723 257/686 257/685 257/777 257/730 257/784 257/786 257/691) and (polymeric polyimide polyimide polymer)) and trace) and (route routing)) and (bond near pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 11:25
–	3	"6420789"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 14:46
–	0	"6522018"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 14:50
–	13	pershelle	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 14:52
–	0	perchelle	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 14:52
–	0	perschelle	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 14:52
–	428	"routing element"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 15:14
–	14	"routing element" and substrate and trace	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 15:14
–	1121	substrate near5 trace and bond near pad	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/13 15:14
–		substrate near5 trace and bond near pad and chip die semiconductor near device	USPAT; US-PGPUB; EPO; JPO; DERWENT	

-	54949	"wiring board"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/19 15:36
-	3165	"wiring board" and carrier	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/19 15:36
-	481	"wiring board" and carrier and trace rout$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/19 15:36
-	186	("wiring board" and carrier and (trace rout$3)) and (bond near pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/20 09:04
-	9397	((multi near chip) multichip) near5 module	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/20 09:11
-	1268	(((multi near chip) multichip) near5 module) and trace and (chip die (semiconductor near device))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/20 10:43
-	617	((((multi near chip) multichip) near5 module) and trace and (chip die (semiconductor near device))) and (bond near pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/20 10:54
-	422	(((((multi near chip) multichip) near5 module) and trace and (chip die (semiconductor near device))) and (bond near pad)) and (polymeric polymer polyimide polymide polym$4 polyim$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/20 10:56
-	404	((((((multi near chip) multichip) near5 module) and trace and (chip die (semiconductor near device))) and (bond near pad)) and (polymeric polymer polyimide polymide polym$4 polyim$4)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/20 11:23
-	116	(((((((multi near chip) multichip) near5 module) and trace and (chip die (semiconductor near device))) and (bond near pad)) and (polymeric polymer polyimide polymide polym$4 polyim$4)) and substrate) and rout$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/20 11:24